WHAT IS CLAIMED IS:

1. A method for forming a light emitting device comprising: aligning a converter layer bonding device over a phosphor, the converter layer bonding device comprising an adhesive layer adhered to a release liner; bringing the adhesive layer and the phosphor into contact at an elevated temperature, the elevated temperature being a temperature at which the adhesive layer adheres to the phosphor; cooling the adhesive layer adhered to the phosphor; removing the release liner from the adhesive layer; bringing one or more LED die into contact with the adhesive layer opposite the phosphor; and heating the adhesive layer, one or more LED die, and phosphor to cure the adhesive layer and form a bond layer between the one or more LED die and the phosphor.

2. The method of claim 1, wherein the adhesive layer is solid and non-adhesive at a first temperature below the elevated temperature.

3. The method of claim 1, wherein the complex shear modulus G* (at 1 Hz) of the adhesive layer at the first temperature is greater than 100 KPa, and the G* (at 1 Hz) of the adhesive layer at the elevated temperature is between 1 KPa and 100 KPa.

4. The method of claim 1, wherein bringing the adhesive layer and the phosphor into contact at an elevated temperature includes applying a vacuum to the converter layer bonding device and the phosphor.

5. The method of claim 1, further including dicing the phosphor and the bonding layer between the one or more LED die.

6. The method of claim 1, further comprising, after removing the release liner, cutting the phosphor and adhesive layer into n×m arrays, and wherein bringing one or more LED die into contact with the adhesive layer opposite the phosphor comprises bringing each of the one or more LED die into contact with an n×m array.

7. The method of claim 1, further comprising cutting channels into the adhesive layer of the converter layer bonding device.

8. The method of claim 1, further comprising: before bringing one or more LED die into contact with adhesive layer, aligning a second converter layer bonding device over the adhesive layer, the second converter layer bonding device comprising a second adhesive layer adhered to a second release liner, a first surface of the second adhesive layer opposite the second release liner facing a second surface of the adhesive layer opposite the phosphor; bringing the first surface of the second adhesive layer and the second surface of the adhesive layer opposite the phosphor into contact at a second elevated temperature, the second elevated temperature being a temperature at which the second adhesive layer adheres to the adhesive layer; cooling the second adhesive layer adhered to the adhesive layer; removing the second release liner from the second adhesive layer; and bringing the one or more LED die into contact with a surface of the second adhesive layer opposite the adhesive layer.